



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **I0408-05**
Product Affected: IDT79RC32H434

DATE: September 07, 2004

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
 Back Mark
 Date Code ZC date code prefix
 Other

Date Effective: October 07, 2004

Contact: Bimla Paul
Title: Product Assurance Manager
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Attachment: Yes No

Samples: Available upon request

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment Device stepping change from "ZB" to "ZC". A minor mask change is being done as a manufacturing improvement. There is no functional changes to the device.
- Material
- Testing
- Manufacturing Site There is no change in die technology/process
- Data Sheet
- Other

RELIABILITY/QUALIFICATION SUMMARY: See attached data. There is no change to die technology/process.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.
IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ **Approval for shipments prior to effective date.**
Name/Date: _____ E-Mail Address: _____
Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT - PCN #: I0408-05

PCN Type: Die Stepping Change

Data Sheet Change: N/A

Detail of Change: Device stepping change from "ZB" to "ZC". A minor mask change is being done as a manufacturing improvement. There is no functional change to the device.

There is no change in die technology/process.

Qualification Test Plan and Results:

Test Vehicle: IDT79RC32434

Qualification Test Plan and Results:

Test Description	Sample Size/# Of Fails	Test Results (SS/# Of Fails)
Dynamic High Temp Operating Life Test ¹	77/0	77/0
* Temperature Cycling (-65 °C to 150 °C, 500 cycle) ¹	45/0	45/0
* Auto Clave (121 °C, 2 ATM, 168 Hrs) ¹	45/0	45/0
Bond Pull ¹	5/0	5/0
Bake & Ball Shear Strength ¹	5/0	5/0
ESD HBM ¹	3/0	3/0
Data Retention Bake	40/0	40/0

Notes: * Test requires Moisture Pre-Conditioning sequence.
1 - Applicable data from ZA qual